INTEGRATED CIRCUITS

DATA SHEET

NE/SA/SE5532/5532A

Internally-compensated dual low noise operational amplifier

Product data Supersedes data of 1997 Sep 29





Internally-compensated dual low noise operational amplifier

NE/SA/SE5532/5532A

DESCRIPTION

The 5532 is a dual high-performance low noise operational amplifier. Compared to most of the standard operational amplifiers, such as the 1458, it shows better noise performance, improved output drive capability and considerably higher small-signal and power bandwidths.

This makes the device especially suitable for application in high-quality and professional audio equipment, instrumentation and control circuits, and telephone channel amplifiers. The op amp is internally compensated for gains equal to one. If very low noise is of prime importance, it is recommended that the 5532A version be used because it has guaranteed noise voltage specifications.

FEATURES

• Small-signal bandwidth: 10 MHz

Output drive capability: 600 Ω, 10 V_{RMS}

Input noise voltage: 5 nV/√Hz (typical)

DC voltage gain: 50000

AC voltage gain: 2200 at 10 kHz

Power bandwidth: 140 kHz

Slew rate: 9 V/μs

Large supply voltage range: ±3 to ±20 V

Compensated for unity gain

PIN CONFIGURATIONS

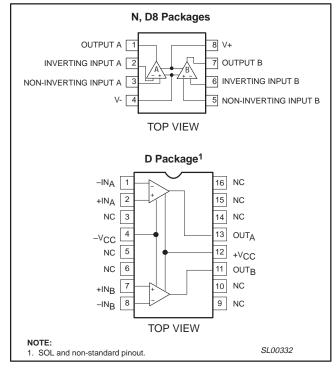


Figure 1. Pin Configurations

ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #
8-Pin Small Outline Package (SO)	0 °C to 70 °C	NE5532AD8	SOT96-1
8-Pin Plastic Dual In-Line Package (DIP)	0 °C to 70 °C	NE5532AN	SOT97-1
16-Pin Plastic Small Outline Large (SOL) Package	0 °C to 70 °C	NE5532D	SOT162-1
8-Pin Small Outline Package (SO)	0 °C to 70 °C	NE5532D8	SOT96-1
8-Pin Plastic Dual In-Line Package (DIP)	0 °C to 70 °C	NE5532N	SOT97-1
8-Pin Plastic Dual In-Line Package (DIP)	−40 °C to +85 °C	SA5532N	SOT97-1
8-Pin Small Outline Package (SO)	−55 °C to +125 °C	SE5532AD8	SOT96-1
16-Pin Plastic Dual In-Line Package (DIP)	–55 °C to +125 °C	SE5532N	SOT38-4

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NE/SA/SE5532/5532A

EQUIVALENT SCHEMATIC (EACH AMPLIFIER)

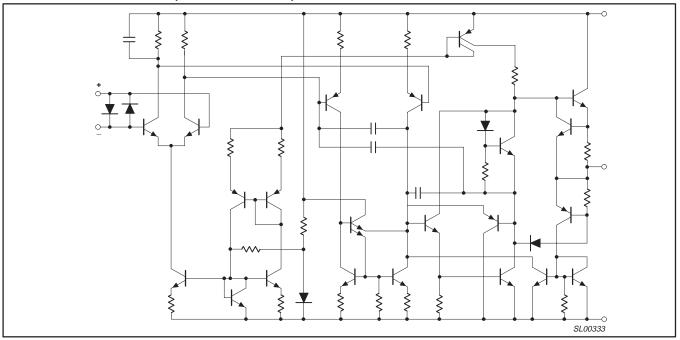


Figure 2. Equivalent Schematic (Each Amplifier)

ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	RATING	UNIT
V _S	Supply voltage	±22	V
V _{IN}	Input voltage	±V _{SUPPLY}	V
V_{DIFF}	Differential input voltage ¹	±0.5	V
T _{amb}	Operating temperature range NE5532/A SA5532 SE5532/A	0 to 70 -40 to +85 -55 to +125	°C °C °C
T _{stg}	Storage temperature	-65 to +150	°C
T _j	Junction temperature	150	°C
P _D	Maximum power dissipation, T _{amb} = 25 °C (still-air) ² 8 D8 package 8 N package 16 D package	780 1200 1200	mW mW mW
T _{sld}	Lead soldering temperature (10 sec max)	230	°C

NOTES:

- Diodes protect the inputs against over-voltage. Therefore, unless current-limiting resistors are used, large currents will flow if the differential input voltage exceeds 0.6V. Maximum current should be limited to ±10 mA.
- 2. Thermal resistances of the above packages are as follows:

N package at 100 °C/W

D package at 105 °C/W

D8 package at 160 °C/W

NE/SA/SE5532/5532A

DC ELECTRICAL CHARACTERISTICS

 T_{amb} = 25 °C; V_S = ±15 V, unless otherwise specified. ^{1, 2, 3}

SYMBOL	DADAMETED	TEST CONDITIONS	,	SE5532/	4	NE55	32/A, S <i>A</i>	\5532	UNIT
STWBUL	PARAMETER	TEST CONDITIONS	Min	Тур	Max	Min	Тур	Max	UNII
V _{OS}	Offset voltage	Over temperature		0.5	2 3		0.5	4 5	mV mV
$\Delta V_{OS}/\Delta T$				5			5		μV/°C
I _{OS}	Offset current	Over temperature			100 200		10	150 200	nA nA
$\Delta I_{OS}/\Delta T$				200			200		pA/°C
I _B	Input current	Over temperature		200	400 700		200	800 1000	nA nA
$\Delta I_B/\Delta T$				5		1	5	1	nA/°C
Icc	Supply current			8	10.5		8	16	mA
		Over temperature			13	1		1	mA
V _{CM}	Common-mode input range		±12	±13		±12	±13		V
CMRR	Common-mode rejection ratio		80	100		70	100		dB
PSRR	Power supply rejection ratio			10	50		10	100	μV/V
A _{VOL}	Large-signal voltage gain	$R_L \ge 2 \text{ k}\Omega; V_O = \pm 10 \text{ V}$ Over temperature $R_L \ge 600 \Omega; V_O = \pm 10 \text{ V}$ Over temperature	50 25 40 20	100 50		25 15 15 10	100 50		V/mV V/mV V/mV V/mV
V _{OUT}	Output swing	$R_L \geq 600~\Omega$ Over temperature $R_L \geq 600~\Omega;~V_S = \pm 18~V$ Over temperature $R_L \geq 2~k\Omega$ Over temperature	±12 ±10 ±15 ±12 ±13 ±12	±13 ±12 ±16 ±14 ±13.5 ±12.5		±12 ±10 ±15 ±12 ±13 ±10	±13 ±12 ±16 ±14 ±13.5 ±12.5		٧
R _{IN}	Input resistance		30	300		30	300		kΩ
I _{SC}	Output short circuit current		10	38	60	10	38	60	mA

- 1. Diodes protect the inputs against overvoltage. Therefore, unless current-limiting resistors are used, large currents will flow if the differential input voltage exceeds 0.6 V. Maximum current should be limited to ± 10 mA.
- For operation at elevated temperature, derate packages based on the package thermal resistance.
 Output may be shorted to ground at V_S = ±15 V, T_{amb} = 25 °C. Temperature and/or supply voltages must be limited to ensure dissipation rating is not exceeded.

AC ELECTRICAL CHARACTERISTICS

 T_{amb} = 25 °C; V_S = ±15 V, unless otherwise specified.

SYMBOL	PARAMETER	TEST CONDITIONS	NE/SE	5532/A, S	SA5532	UNIT
STWIBUL	PARAMETER	TEST CONDITIONS	Min	Тур	Max	UNII
R _{OUT}	Output resistance	A_V = 30 dB Closed-loop f = 10 kHz, R_L = 600 Ω		0.3		Ω
	Overshoot	Voltage-follower $V_{IN} = 100 \text{ mV}_{P-P}$ $C_L = 100 \text{ pF; } R_L = 600 \Omega$		10		%
A _V	Gain	f = 10 kHz		2.2		V/mV
GBW	Gain bandwidth product	$C_L = 100 \text{ pF}; R_L = 600 \Omega$		10		MHz
SR	Slew rate			9		V/μs
	Power bandwidth	V_{OUT} = ±10 V V_{OUT} = ±14 V; R _L = 600 Ω , V_{CC} =±18V		140 100		kHz kHz

NE/SA/SE5532/5532A

ELECTRICAL CHARACTERISTICS

 T_{amb} = 25 °C; V_S = ±15 V, unless otherwise specified.

SYMBOL	PARAMETER	TEST CONDITIONS	N	E/SE553	32	NE/S	A/SE55	UNIT	
STIMBUL	PARAMETER	TEST CONDITIONS	Min	Тур	Max	Min	Тур	Max	UNII
V _{NOISE}	Input noise voltage	f _O = 30 Hz f _O = 1 kHz		8 5			8 5	12 6	nV/√ Hz nV/√ Hz
I _{NOISE}	Input noise current	f _O = 30 Hz f _O = 1 kHz		2.7 0.7			2.7 0.7		pA/√ Hz pA/√ Hz
	Channel separation	$f = 1 \text{ kHz}; R_S = 5 \text{ k}\Omega$		110			110		dB

TYPICAL PERFORMANCE CHARACTERISTICS

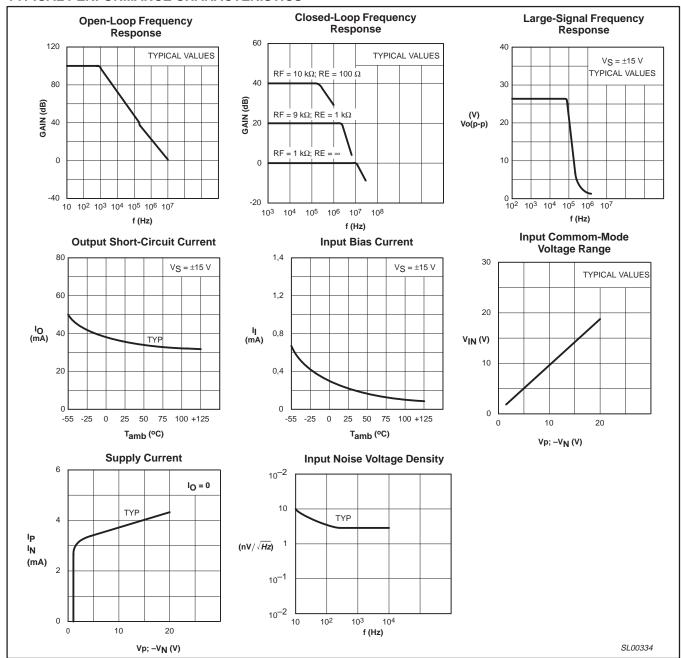


Figure 3. Typical Performance Characteristics

2001 Aug 03 5

Internally-compensated dual low noise operational amplifier

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TEST CIRCUITS

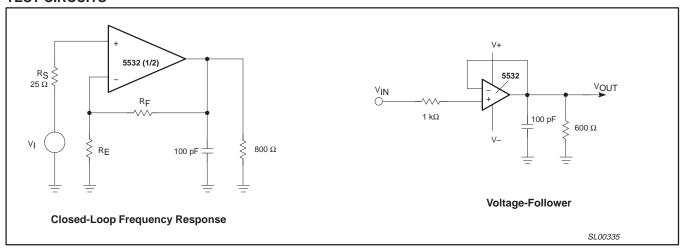
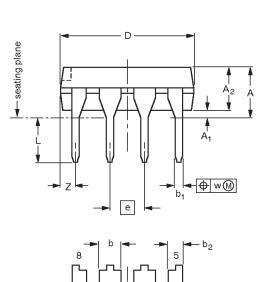


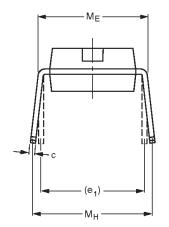
Figure 4. Test Circuits

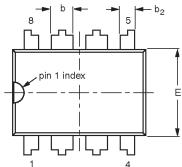
NE/SA/SE5532/5532A

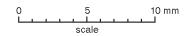
DIP8: plastic dual in-line package; 8 leads (300 mil)

SOT97-1









DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.14	0.53 0.38	1.07 0.89	0.36 0.23	9.8 9.2	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	1.15
inches	0.17	0.020	0.13	0.068 0.045	0.021 0.015	0.042 0.035	0.014 0.009	0.39 0.36	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.045

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

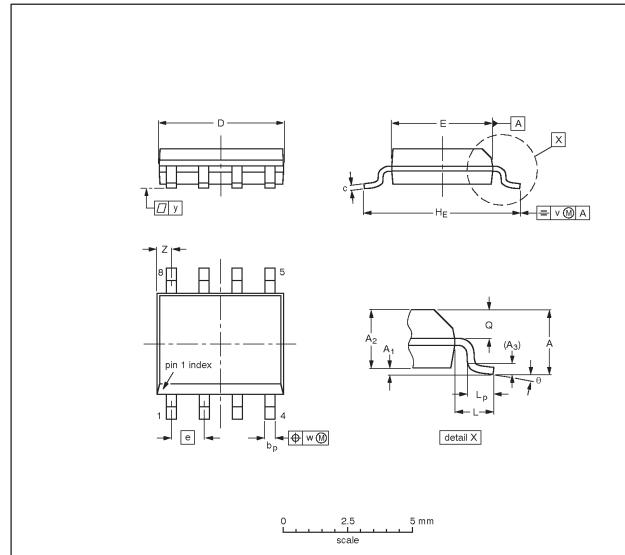
OUTLINE		REFEF	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT97-1	050G01	MO-001	SC-504-8		95-02-04 99-12-27

2001 Aug 03 7

NE/SA/SE5532/5532A

SO8: plastic small outline package; 8 leads; body width 3.9 mm

SOT96-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	Ьp	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.20 0.19	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

Notes

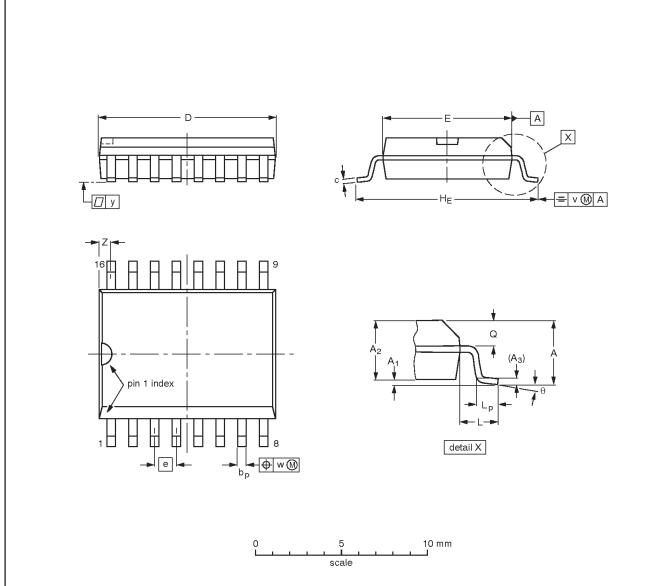
- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	1330E DATE
SOT96-1	076E03	MS-012			97-05-22 99-12-27

NE/SA/SE5532/5532A

SO16: plastic small outline package; 16 leads; body width 7.5 mm

SOT162-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

Note

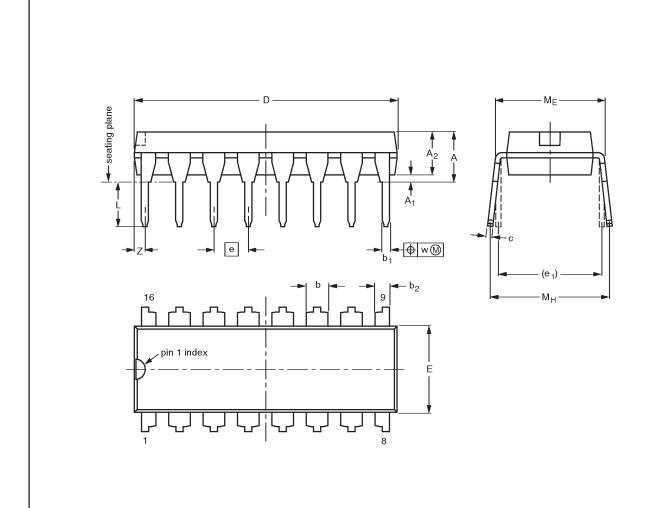
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT162-1	075E03	MS-013			-97-05-22 99-12-27

NE/SA/SE5532/5532A

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



0 5 10 mm scale

DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	c	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

	OUTLINE VERSION	REFERENCES				EUROPEAN	ISSUE DATE
		IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
	SOT38-4						92-11-17 95-01-14

2001 Aug 03 10

Internally-compensated dual low noise operational amplifier

NE/SA/SE5532/5532A

NOTES

Internally-compensated dual low noise operational amplifier

NE/SA/SE5532/5532A

Data sheet status

Data sheet status ^[1]	Product status ^[2]	Definitions
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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